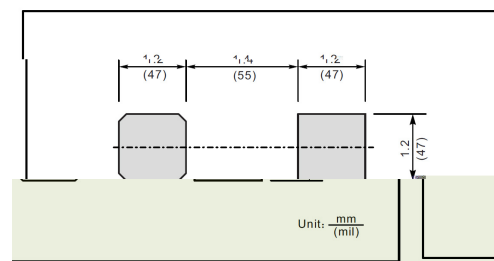


SOD-323

Schottky Diode in a SOD-323 Plastic Package.

Low positive pressure $\ddot{E}$ }^r ^r $\ddot{E}$ No $\ddot{E}$ o $\ddot{E}$ u u t
M

The recommended mounting pad size



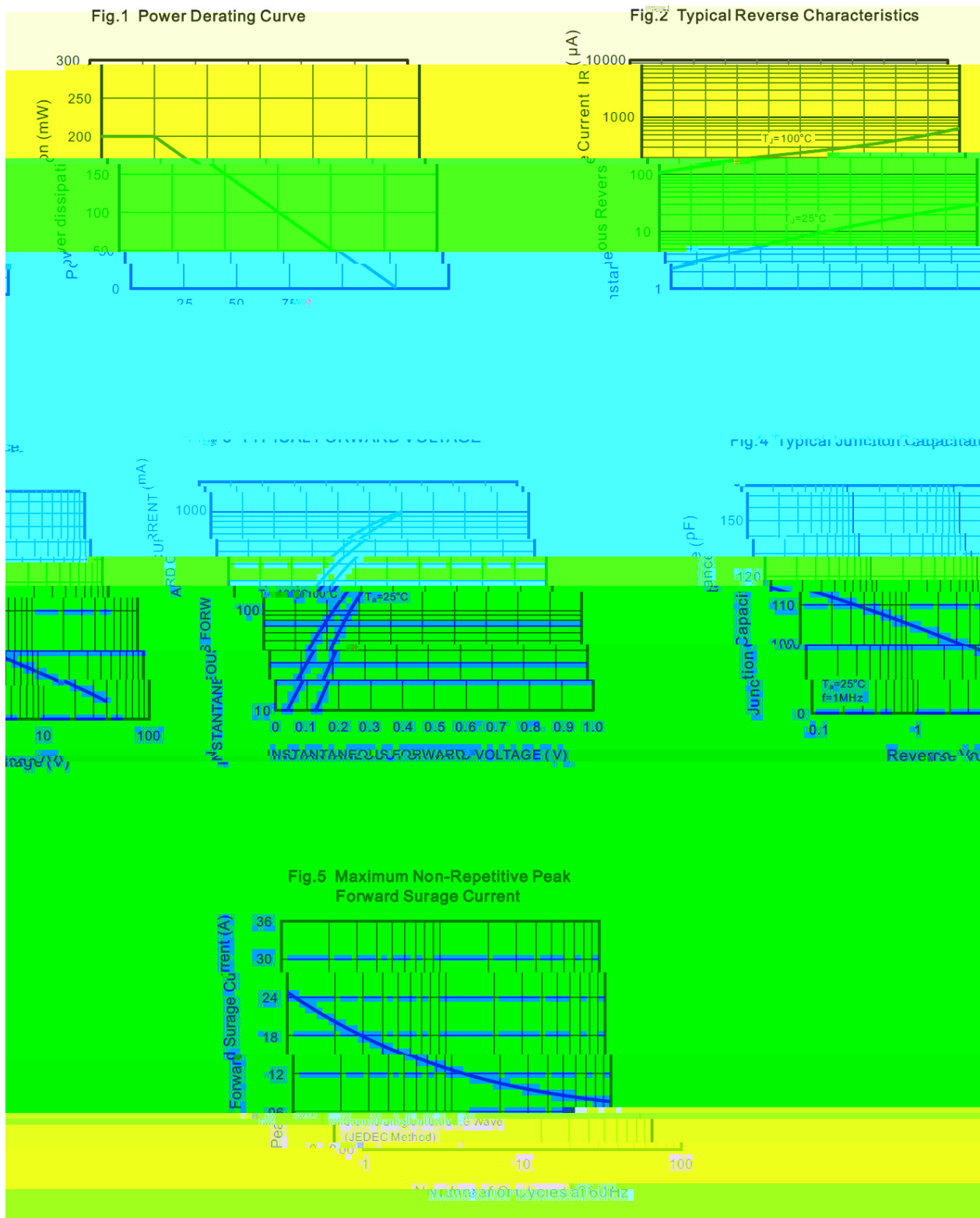
/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Maximum recurrent peak reverse voltage	V_{RM}	40	V
Continuous forward current	I_O	500	mA
Peak Forward Surge Current, 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	25	A
Total power dissipation	P_D	200	mW
Thermal Resistance, Junction to Ambient Air	$R_{\theta JA}$	400	$^{\circ}\text{C}/\text{W}$
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-55 ~ +150	

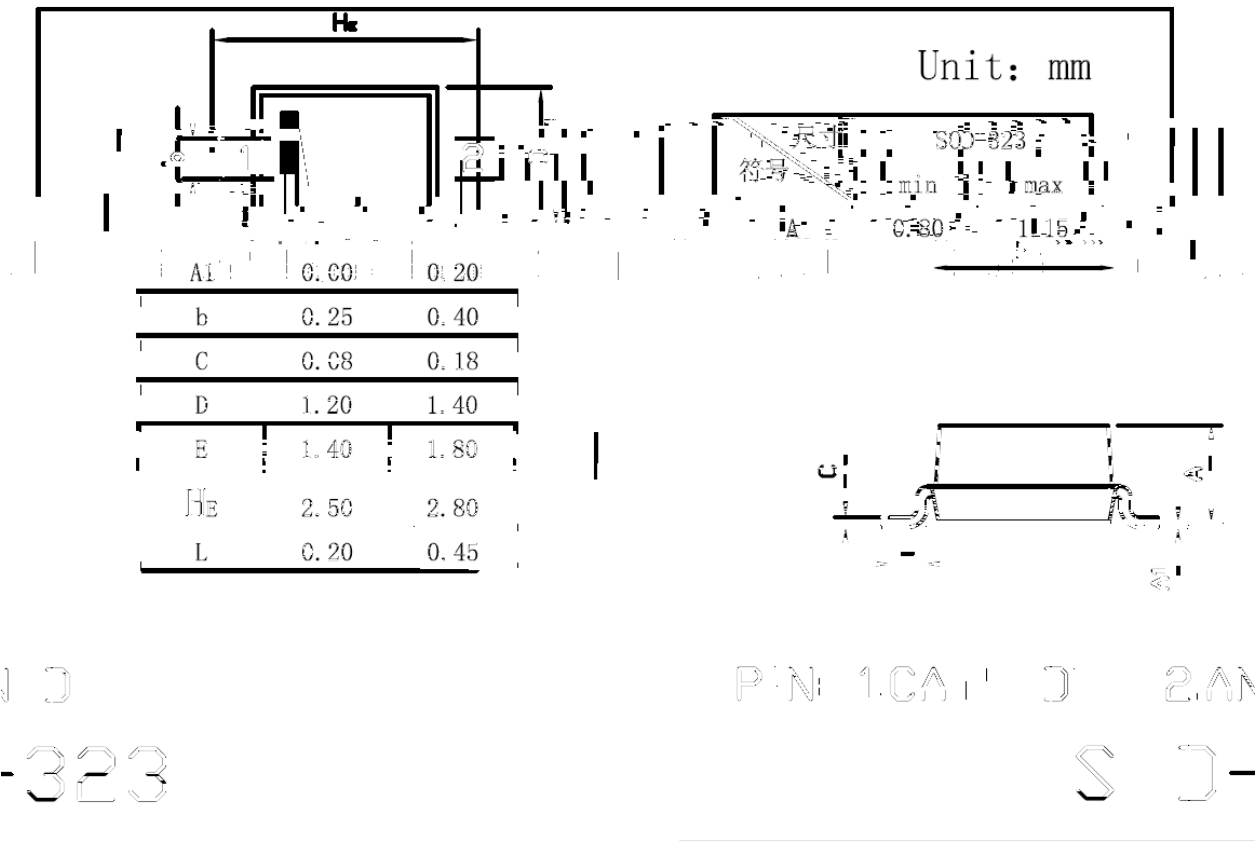
/ Electrical Characteristics($T_a=25^\circ\text{C}$)

Parameter	Symbol	Test Conditions	Rating	Unit
Maximum Forward Voltage	V_F	$I_F=0.5\text{A}$	0.47	V
Reverse Leakage Current	I_R	$V_R=40\text{V}$	0.1	mA

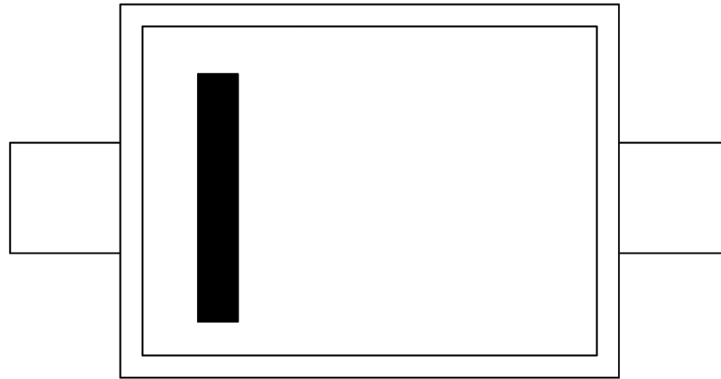
/ Electrical Characteristic Curve



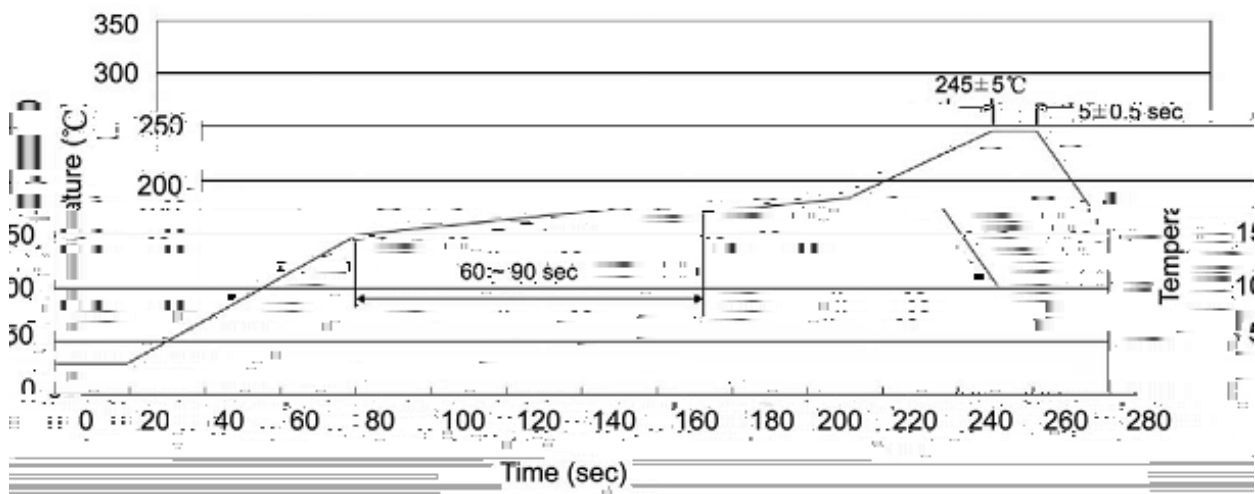
/ Package Dimensions



/ Marking Instructions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245±5

5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOD-323	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205